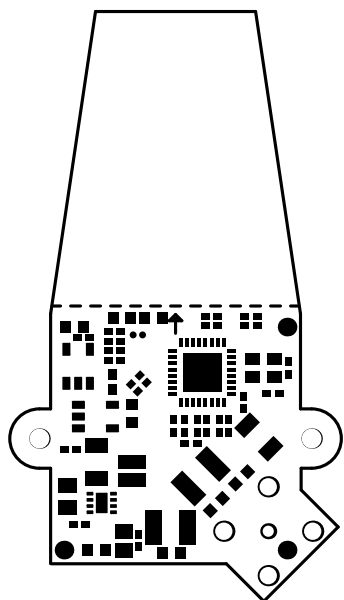
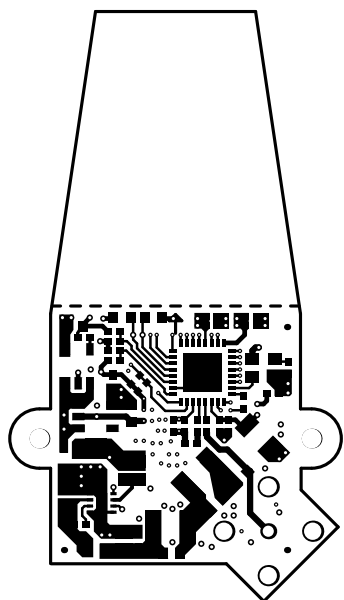


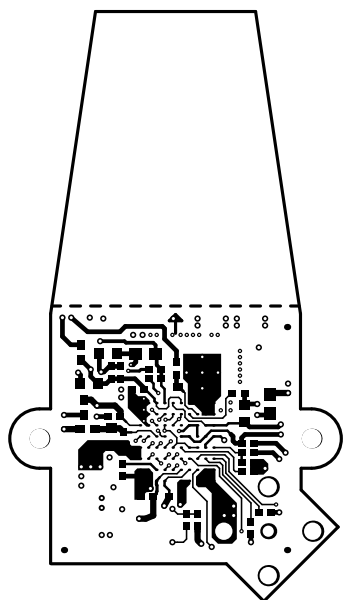
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/9/2018	8:56:01 AM	TEXAS INSTRUMENTS



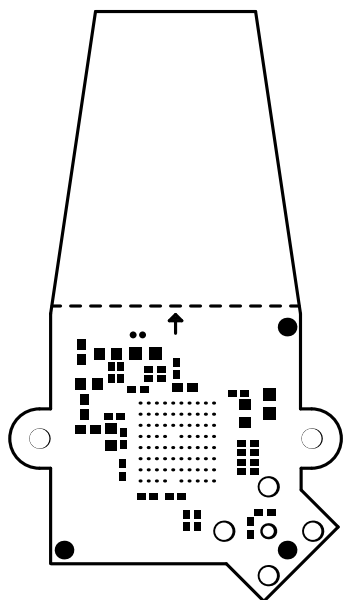
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/9/2018 8:56:02 AM	TEXAS INSTRUMENTS	



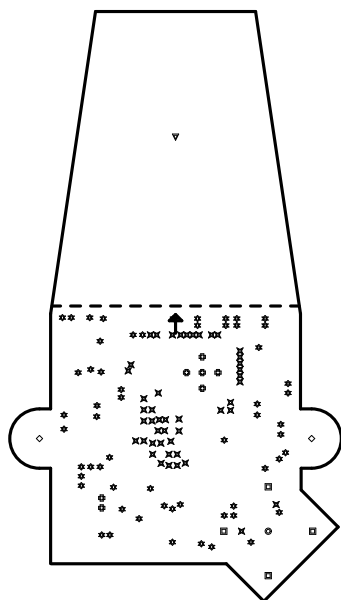
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/9/2018	8:56:03 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Layer 6 - Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/9/2018 8:56:04 AM	TEXAS INSTRUMENTS	

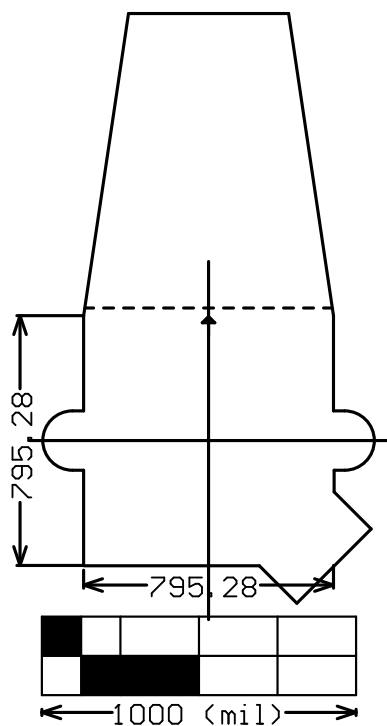


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/9/2018 8:56:05 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	2	62.99mil (1.600mm)	NPTH	Round
▽	1	280.00mil (7.112mm)	NPTH	Round
✕	46	6.00mil (0.152mm)	PTH	Round
⊕	7	7.87mil (0.200mm)	PTH	Round
☆	59	10.00mil (0.254mm)	PTH	Round
⊙	1	35.43mil (0.900mm)	PTH	Round
⊠	4	55.12mil (1.400mm)	PTH	Round
	120 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/9/2018	8:56:07 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01392	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/9/2018	8:56:08 AM	TEXAS INSTRUMENTS

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